



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/ContentPage.aspx?pageid=Materials-Declaration>

Form Type*
 Distribute

Declaration Class*
 Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Mar 24, 2015
Contact Name * Jolene Small	Title - Contact Product Ecology	Phone - Contact * 207-761-6214	Email - Contact * jolene.small@fairchildsemi.com
Authorized Representative * Jolene Small	Title - Representative Product Ecology	Phone - Representative * 207-761-6214	Email - Representative * jolene.small@fairchildsemi.com


Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	FSC Version	Manufacturing Site	Weight*	UOM	Unit Type
FDMF6706B	FDMF6706B	PQFN-40.csv	Mar 24, 2015	1.0	FSCP	0.134312	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Copper Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions Supplier Acceptance * Accepted		
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
<p>Exemption List Version EL-2011/534/EU</p> <p>7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).</p>		

Declaration Signature	
Supplier Signature	 JOLENE SMALL – PRODUCT ECOLOGY ENGINEER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name PQFN-40.csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.096	Supplier		Silicon	0.096	7440-21-3	715
Die Attach	Other Nonferrous metals & alloys	5.1	A	Lead/Lead Compounds	Lead	4.718	7439-92-1	35123
			Supplier		Silver	0.128	7440-22-4	949
			Supplier		Tin	0.255	7440-31-5	1899
Encapsulation	Thermoplastics	63.216	Supplier		Carbon Black	0.316	1333-86-4	2353
			Supplier		Epoxy Resin	3.79	29690-82-2	28218
			Supplier		Phenolic resin	2.21	9003-35-4	16454
			Supplier		Silica, vitreous	56.9	60676-86-0	423640
Lead Frame	Copper & its alloys	44.2	Supplier		Copper	43.1	7440-50-8	320894
			Supplier		Iron	0.998	7439-89-6	7430
			Supplier		Silver	0.054	7440-22-4	398
			Supplier		Zinc	0.049	7440-66-6	362
Lead Frame Clip	Copper & its alloys	19.6	Supplier		Copper	19.6	7440-50-8	145929
Terminal Finish	Other Nonferrous metals & alloys	2	Supplier		Tin	2	7440-31-5	14891
Wire Bond	Precious metals	0.1	Supplier		Gold	0.1	7440-57-5	745